

What is claimed is:

1. A system for delivering a polishing fluid to a chemical mechanical polishing surface comprising:

an arm having a delivery portion disposed at least partially over the polishing surface;

a first nozzle disposed on the delivery portion and adapted to flow the polishing fluid at a first rate; and

at least a second nozzle disposed on the delivery portion and adapted to flow the polishing fluid at a second rate that is different than the first rate.

2. The system of claim 1 further comprising a flow control device coupled to the first nozzle.

3. The system of claim 2 further comprising a second control device coupled to the second nozzle.

4. The system of claim 2, wherein the flow control device is a flow control selected from the group consisting of orifices, needle valves, proportional valves, pinch valves, restrictors, mass flow controllers and a metering pumps.

5. The system of claim 1, wherein the arm further comprises a polishing fluid delivery line coupled to both the first and second nozzle.

6. The system of claim 1 further comprising a first fluid source coupled to the first nozzle and a second fluid source coupled to the second nozzle.

7. The system of claim 1 further comprising a plurality of nozzles adapted to flow polishing fluid at a controlled rate.

8. The system of claim 7, wherein each nozzle is independently controllable.

- a first means for providing polishing fluid to the polishing surface at a first rate; and



flowing the polishing fluid onto the pad at a first location at a first rate; and  
flowing the polishing fluid on the pad at a second location at a second rate  
that is different than the first rate.

24. The method of claim 23, wherein the first rate is independently controllable  
relative the second rate.

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25. The method of claim 23 further comprising:  
flowing the polishing fluid on the pad at one or more locations between the  
first location and the second location.

26. The method of claim 23, wherein the step of flowing the polishing fluid at a  
first rate further comprises:  
adjusting the flow rate during polishing.

27. The method of claim 26, wherein the step of adjusting further comprises:  
adjusting the flow rate in response to a polishing metric.

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